

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TORU MASUDA	11/05/2020
SEIICHI HAYAKAWA	11/05/2020
YUJI TAKAYANAGI	11/05/2020
TAKAE SHIMADA	11/09/2020
TAKASHI WADA	11/05/2020
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17172571
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SIGNATURE:	/Michael H. Jacobs/
DATE SIGNED:	05/13/2021
Total Attachments: 1	
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ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi Power Semiconductor Device, Ltd., a corporation organized under the laws of Japan, located at 2-2, Omika-cho 5-chome, Hitachi-shi, Ibaraki, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi Power Semiconductor Device, Ltd., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR DEVICE SIGNAL TRANSMISSION CIRCUIT FOR DRIVE-CONTROL, METHOD OF CONTROLLING SEMICONDUCTOR DEVICE SIGNAL TRANSMISSION CIRCUIT FOR DRIVE-CONTROL, SEMICONDUCTOR DEVICE, POWER CONVERSION DEVICE, AND ELECTRIC SYSTEM FOR RAILWAY VEHICLE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi Power Semiconductor Device, Ltd., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi Power Semiconductor Device, Ltd.,

Signed on the date(s) indicated aside signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	Toru MASUDA <u>Toru Masuda</u>	<u>November 5, 2020</u>
2)	Seiichi HAYAKAWA <u>Seiichi Hayakawa</u>	<u>November 5, 2020</u>
3)	Yuji TAKAYANAGI <u>Yuji Takayanagi</u>	<u>November 5, 2020</u>
4)	Takae SHIMADA <u>Takae Shimada</u>	<u>November 9, 2020</u>
5)	Takashi WADA <u>Takashi Wada</u>	<u>November 5, 2020</u>
6)	_____	_____
7)	_____	_____
8)	_____	_____
9)	_____	_____